

GenX3[™] 600V IGBT with Diode

Test Conditions

 $T_1 = 25^{\circ}C \text{ to } 150^{\circ}C$

 $T_{\perp} = 25^{\circ}\text{C} \text{ to } 150^{\circ}\text{C}, R_{\text{GF}} = 1\text{M}\Omega$

IXGH48N60C3D1

High speed PT IGBT for 40-100kHz Switching

Symbol

V_{CES}

V_{CGR}

 \mathbf{F}_{c}

Weight



Maximum Ratings

600

600

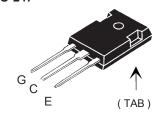
1.13/10

Nm/lb.in

g

V _{CES}	= 600V
C110	= 48A
V _{CE(sat)}	≤ 2.5 V
t _{fi(typ)}	= 38ns





G = Gate	С	=	Collector
E = Emitter	TAB	=	Collector

can	3 GE		
V _{GES}	Continuous	±20	V
V _{GEM}	Transient	±30	V
I _{C25}	T _c = 25°C (Limited by Leads)	75	Α
I _{C110}	$T_{C} = 110^{\circ}C$	48	Α
I _{D110}	$T_{c} = 110^{\circ}C$	30	Α
I _{CM}	$T_{c} = 25^{\circ}C$, 1ms	250	Α
I _A	T _C = 25°C	30	Α
E _{AS}	$T_{c} = 25^{\circ}C$	300	mJ
SSOA	$V_{GE} = 15V, T_{VJ} = 125^{\circ}C, R_{G} = 3\Omega$	I _{CM} = 100	Α
(RBSOA)	Clamped Inductive Load	$@V_{CE} \le 600$	V
P _c	T _c = 25°C	300	W
T _J		-55 +150	°C
T_JM		150	°C
T_{stg}		-55 +150	°C
T _L	1.6mm (0.062 in.) from Case for 10s	300	°C
T _{SOLD}	Plastic Body for 10 Seconds	260	°C

Features

- Optimized for Low Switching Losses
- Square RBSOA
- Anti-Parallel Ultra Fast Diode
- Fast Switching
- Avalanche Rated
- International Standard Package

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

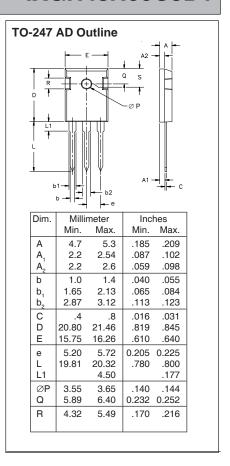
- High Frequency Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol Test Conditions			Characteristic Values				
$(T_J = 25^{\circ}C$, Unless	Otherwise Specified)		Min.	Тур.	Max	
V _{GE(th)}	I _c	= 250 μ A, $V_{CE} = V_{GE}$		3.0		5.5	V
I _{CES}	${\sf V}_{\sf CE} \ {\sf V}_{\sf GE}$	= V _{CES} = 0V	T _J = 125°C			300 1.75	μA mA
I _{GES}	V _{CE}	$= 0V, V_{GE} = \pm 20V$				±100	nA
V _{CE(sat)}	I _c	= 30A, V _{GE} = 15V, Not	te 1 Γ _J = 125°C		2.3 1.8	2.5	V V

Mounting Torque



Symbol Test Conditions Chara			c Value	s
$(T_J = 25^{\circ}C, Unless Otherwise Specified)$ Mir	ı. T	ур.	Max.	
g_{fs} $I_{C} = 30A, V_{CE} = 10V, Note 1 2$	o :	30		S
C _{ies}	19	60		pF
C_{oes} $V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$	2	02		pF
C _{res}		66		pF
Q_g		77		nC
\mathbf{Q}_{ge} $\left\{ I_{C} = 30A, V_{GE} = 15V, V_{CE} = 0.5 \bullet V_{CES} \right\}$		16		nC
Q_{gc}		32		nC
$t_{d(on)}$		19		ns
t _{ri} Inductive Load, T ₁ = 25°C		26		ns
E_{on} $I_{c} = 30A, V_{GE} = 15V$	0.4	41		mJ
$\mathbf{t}_{d(off)}$ $\sqrt{V_{CE}} = 400V, R_{G} = 3\Omega$		60	100	ns
t _{fi}		38		ns
E _{off}	0.	23	0.42	mJ
t _{d(on)}		19		ns
Inductive Load, T _J = 125°C	:	26		ns
E_{on} $I_{\text{C}} = 30A, V_{\text{GF}} = 15V$	0.	65		mJ
$t_{d(off)}$ $V_{CF} = 400V, R_G = 3\Omega$	'	92		ns
t _{fi}		95		ns
E _{off}	0.	57		mJ
R _{thJC}			0.42	°C/W
R _{thCS}	0.	21		°C/W



Reverse Diode (FRED)

Characteristic Values

(T_J = 25°C, Unless Otherwise Specified)

Symbo	ol Test Conditions	Min.	Тур.	Max.	
V_	I _F = 30A, V _{GF} = 0V, Note 1			2.7	V
	, GE	$T_J = 150^{\circ}C$	1.6		V
I _{RM}	$I_F = 30A$, $V_{GE} = 0V$, $-di_F/dt = 100A/\mu s$, $V_R = 100V$	T _J = 100°C T _J = 100°C	100	4	A ns
	$I_F = 1A, V_{GE} = 0V, -di_F/dt = 100A/\mu s, V_R = 3$	30 V	25		ns
R_{thJC}				0.9 °C	C/W

Note 1: Pulse Test, $t \le 300\mu s$, Duty Cycle, $d \le 2\%$.

Fig. 1. Output Characteristics @ 25°C

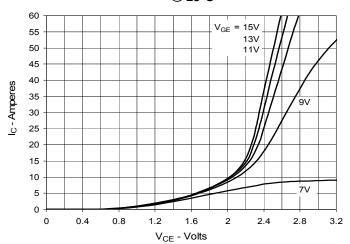


Fig. 2. Extended Output Characteristics
@ 25°C

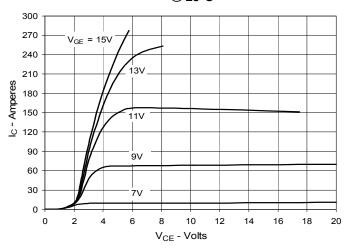


Fig. 3. Output Characteristics @ 125°C

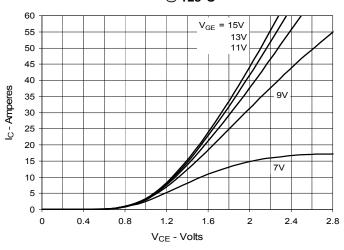


Fig. 4. Dependence of V_{CE(sat)} on Junction Temperature

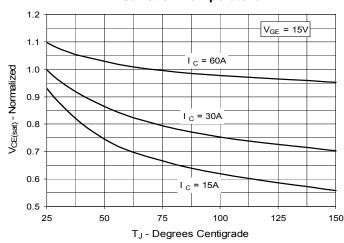


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

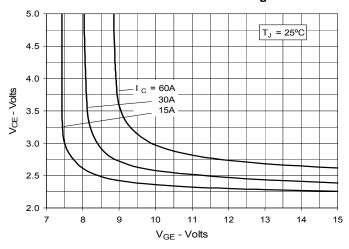
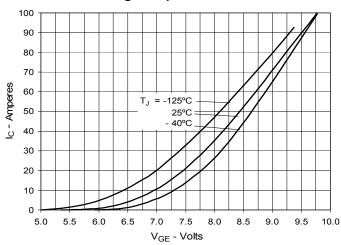
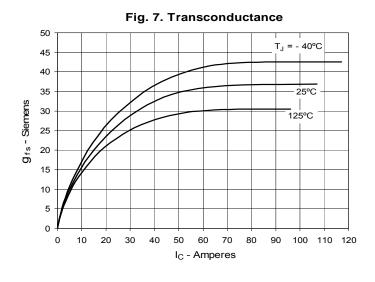
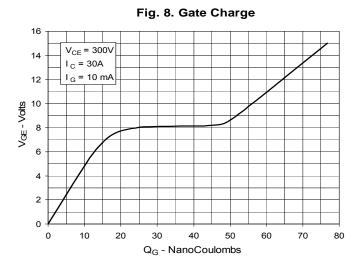
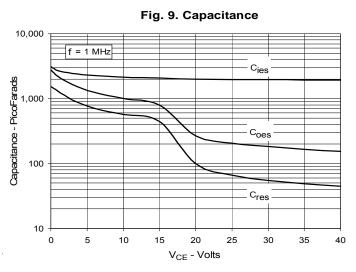


Fig. 6. Input Admittance









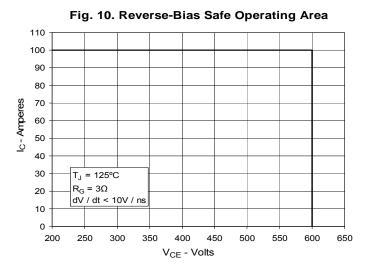
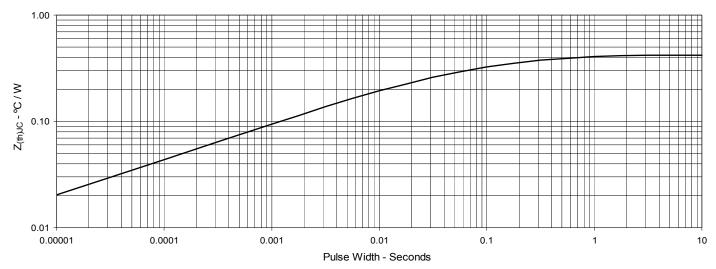


Fig. 11. Maximum Transient Thermal Impedance



IXYS reserves the right to change limits, test conditions, and dimensions.



Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

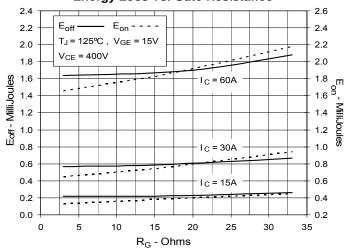


Fig. 14. Inductive Swiching

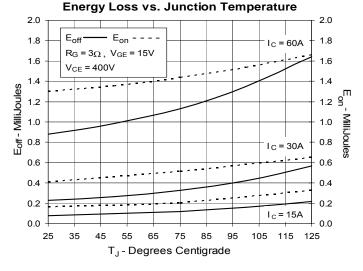


Fig. 16. Inductive Turn-off

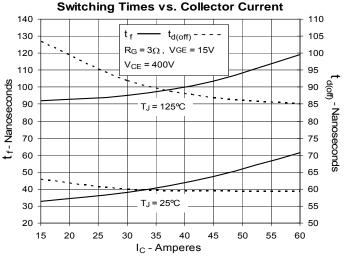


Fig. 13. Inductive Swiching Energy Loss vs. Collector Current

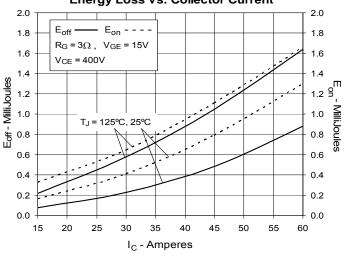


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

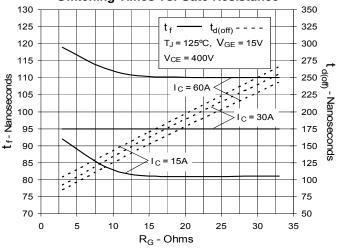


Fig. 17. Inductive Turn-off
Switching Times vs. Junction Temperature

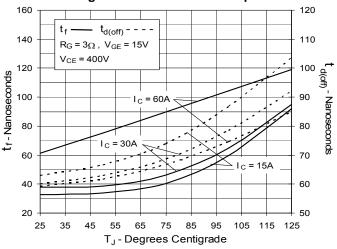




Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

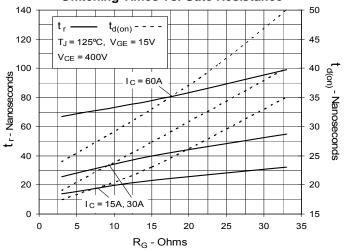


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

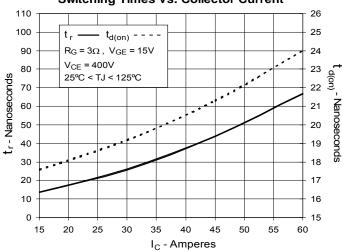
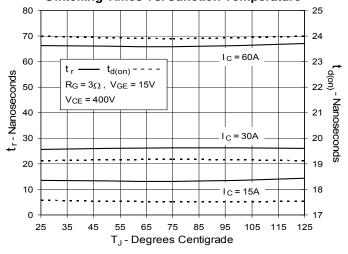


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature



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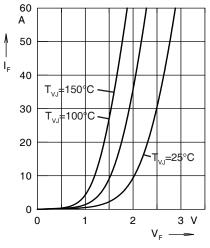


Fig. 21. Forward current I_F versus V_F

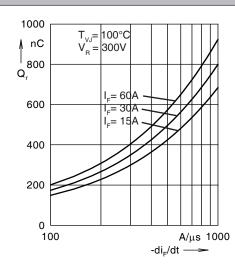


Fig. 22. Reverse recovery charge Q_r versus -di_r/dt

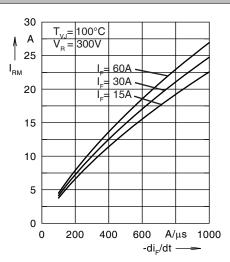


Fig. 23. Peak reverse current I_{RM} versus -di₋/dt

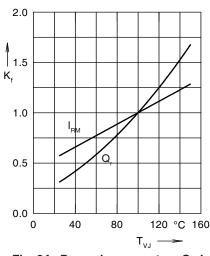


Fig. 24. Dynamic parameters Q_r, I_{RM} versus T_{v,i}

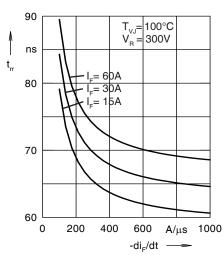


Fig. 25. Recovery time t_{rr} versus $-di_{\it r}/dt$

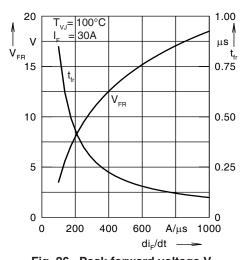


Fig. 26. Peak forward voltage $V_{\rm FR}$ and $t_{\rm fr}$ versus $di_{\rm f}/dt$

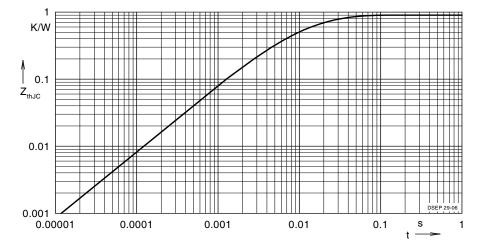


Fig. 27. Transient thermal resistance junction to case

Constants for Z_{thJC} calculation:

i	R _{thi} (K/W)	t _i (s)
1	0.502	0.0052
2	0.193	0.0003
3	0.205	0.0162